

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No. 09/546,174	Confirmation No.: 4793
Application of: Chih-Chien Liu, Ta-Shan Tseng, W. B. Shieh, J. Y. Wu, Water Lur and Shih-Wei Sun	Customer No.: 25235
Filed: April 11, 2000	
Art Unit: 1711	
Examiner: Sergeant, Rabon A.	
Attorney Docket No. UMC-96-279 CON	
For: HIGH DENSITY PLASMA CHEMICAL VAPOR DEPOSITION PROCESS	

AMENDMENT AND RESPONSE PURSUANT TO OFFICE ACTION DATED
FEBRUARY 22, 2006

MAIL STOP Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the office communication mailed February 22, 2006,
please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which
begins on page 2 of this paper.

Remarks/Arguments begin on page 11 of this paper.

Petition for One Month Extension of Time with \$120 fee is attached
following page 13 of this paper.